

Amendments to the Claims:

Please amend claims 74-81, and cancel claim 73. Following is a complete listing of the claims pending in the application, as amended:

1-72. (Cancelled)

73. (Cancelled)

74. (Currently amended) The assembly of claim 73-76 wherein each elongated member is configured to receive at least a portion of the flowable conductive material from the second bond site.

75. (Currently amended) The assembly of claim 73-76 wherein the connection structure is a first connection structure and the at least two elongated members are inactive elongated members, and wherein the assembly further comprises:

a second connection structure disposed on the second surface of the microelectronic substrate, the second connection structure having a third bond site configured to receive a flowable conductive material, the second connection structure further having at least two active elongated members connected to and extending outwardly away from the third bond site, and wherein at least one of the active elongated members is electrically coupled to the first bond site of the microelectronic substrate.

76. (Currently amended) The assembly of claim 73-A microelectronic assembly, comprising:

a microelectronic substrate having a first surface, a second surface facing opposite from the first surface, and a first bond site positioned at least proximate to the second surface; and

a connection structure disposed on the second surface of the microelectronic substrate, the connection structure having a second bond site configured

to receive a flowable conductive material, the connection structure further having at least two elongated members connected to and extending outwardly from the second bond site, wherein none of the elongated members of the connection structure are connected to any bond sites of the microelectronic substrate.

77. (Currently amended) The assembly of claim 7376, further comprising a volume of flowable conductive material disposed on the second bond site.

78. (Currently amended) The assembly of claim 7376 wherein the connection structure includes a metal redistribution layer deposited on the microelectronic substrate.

79. (Currently amended) The assembly of claim 7376 wherein the microelectronic substrate has a first surface and a second surface facing opposite from the first surface, and wherein the first bond site is positioned at least proximate to the second surface, further wherein the elongated members are spaced apart from the second surface in a plane generally parallel to the second surface.

80. (Withdrawn-Currently amended) The assembly of claim 7376 wherein the microelectronic substrate has a first surface and a second surface facing opposite from the first surface, and wherein the first bond site is positioned at least proximate to the second surface, and wherein the elongated members each have a first surface and a second surface facing opposite from the first surface, and wherein the assembly further comprises:

- a first passivation layer between the second surface of the microelectronic substrate and the first surfaces of the elongated members;
- a second passivation layer adjacent to the second surfaces of the elongated members; and
- a conductive coupler disposed on the second bond site, the conductive coupler including a flowable conductive material.

81. (Withdrawn-Currently amended) The assembly of claim 73-76 wherein the microelectronic substrate has a first surface and a second surface facing opposite from the first surface, and wherein the first bond site is positioned at least proximate to the second surface in a first plane generally parallel to the second surface, further wherein the second bond site is positioned in a second plane generally parallel to and spaced apart from the first plane.

82-123. (Cancelled)

124. (Withdrawn) An electronic device, comprising:
a microelectronic substrate having a plurality of bond pads; and
a connection structure disposed on the microelectronic substrate, the connection structure having a bond site configured to receive a flowable conductive material, the connection structure further having at least two elongated members, each of which is connected to and extends outwardly from the bond site, each elongated member being configured to receive at least a portion of the flowable conductive material from the bond site, and neither of which is electrically connected to one of the bond pads.

125. (Withdrawn) The device of claim 124 wherein each elongated member is configured to receive at least a portion of the flowable conductive material from the bond site.

126. (Withdrawn) The device of claim 124 wherein the connection structure is a first connection structure and the elongated members are first elongated members configured to receive at least a portion of the flowable conductive material from the first bond site, wherein the device further comprises a second connection structure carried by the microelectronic substrate, the second connection structure having a second bond site configured to receive a flowable conductive material, the second connection structure further having second elongated members extending outwardly from the second bond site, wherein each of the second elongated members is configured to

receive at least a portion of the flowable conductive material, and wherein at least one of the second elongated members extends between the second bond site and one of the bond pads.

127. (Withdrawn) The device of claim 124 wherein the elongated members are configured to be wetted by the flowable conductive material when the flowable conductive material is in a flowable state.

128. (Withdrawn) The device of claim 124 wherein the two elongated members extend away from opposite sides of the bond site.

129. (Withdrawn) The device of claim 124, further comprising a layer disposed on the elongated members and attached to the microelectronic substrate, the layer having an aperture aligned with the bond site.

130. (Withdrawn) The device of claim 124, further comprising a layer disposed on the elongated members and attached to the microelectronic substrate, the layer having an aperture aligned with the bond site, and wherein a covered portion of each elongated member extends between the layer and the microelectronic substrate, and an exposed portion of each elongated member is exposed through the aperture, further wherein each exposed portion has approximately the same length.

131. (Withdrawn) The device of claim 124 wherein the connection structure includes at least one electrically conductive metallic material.

132. (Withdrawn) The device of claim 124 wherein the bond site includes a solder ball pad, and wherein the device further comprises a solder ball disposed on the solder ball pad.

133. (Withdrawn) The device of claim 124 wherein at least one of the elongated members has a first end connected to the bond site and a second end

spaced apart from the bond site, and wherein the elongated member includes an anchor toward the second end to secure the elongated member to the microelectronic substrate.

134. (Withdrawn) The device of claim 124, further comprising a housing, wherein the microelectronic substrate is positioned within the housing.